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Substrate: 0.635mm ±0.18mm [0.025" ±0.007"] per IPC 4101/21, Gold surface finish.



Substrate: 1.59mm ± 0.18 mm $[0.062" \pm 0.007"]$ FR4/G10 or equivalent high temp material. Non-clad.



Pins: shell material- Brass Alloy 360 1/2 hard; finish- $0.25\mu m [10\mu"]$ Au over $1.27\mu m [50\mu"]$ Ni (min.). Contact material- BeCu; finish $0.25\mu m [10\mu"]$ Au over $2.54\mu m [100\mu"]$ Ni (min.).

Rohs Compliant

<u>Description:</u> 40 position MLF/QFN surface mount foot 40 position (+1 Gnd index pin). 0.75mm pitch UGA female receptacles (top) to 40 position, 0.5mm MLF/QFN pattern

<u>Tolerances:</u> diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-QFN40A-L-02 Drawing	Status: Released	Scale	: 8:1	Rev: B
© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 5/13/06	
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